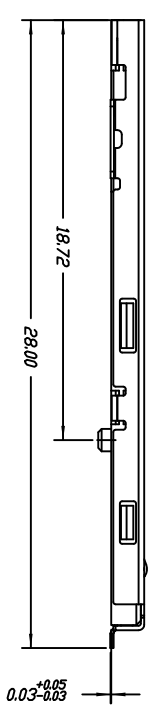
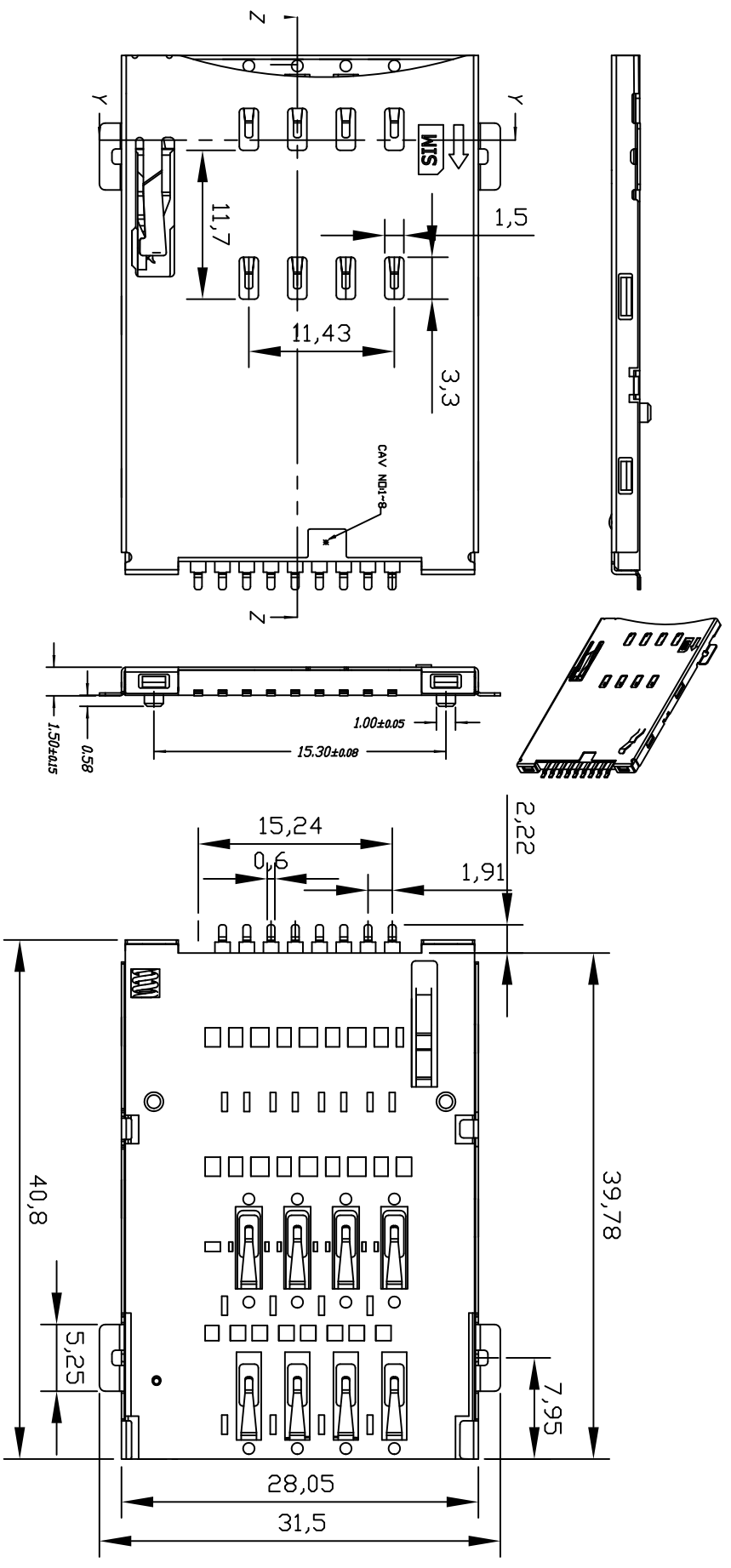


REV	DESCRIPTION	ECN NO	DATE

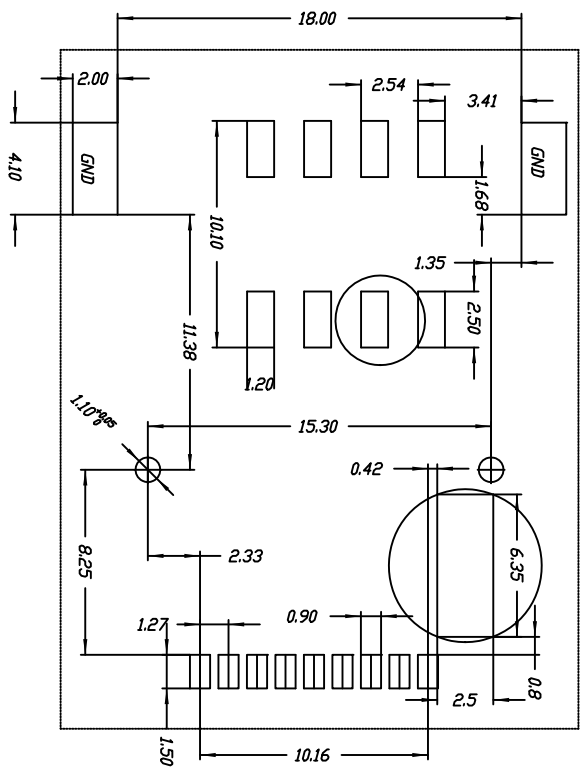


GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		TITLE:	
XX	±0.25	DRAWN BY:	DATE	SIM Card Push T=1.50	
X.XX	±0.15	Checked BY:	DATE	PART NO:	
X.XXX	±0.05	APPERIAL BY:	DATE	SIM-008<新改版-A>	

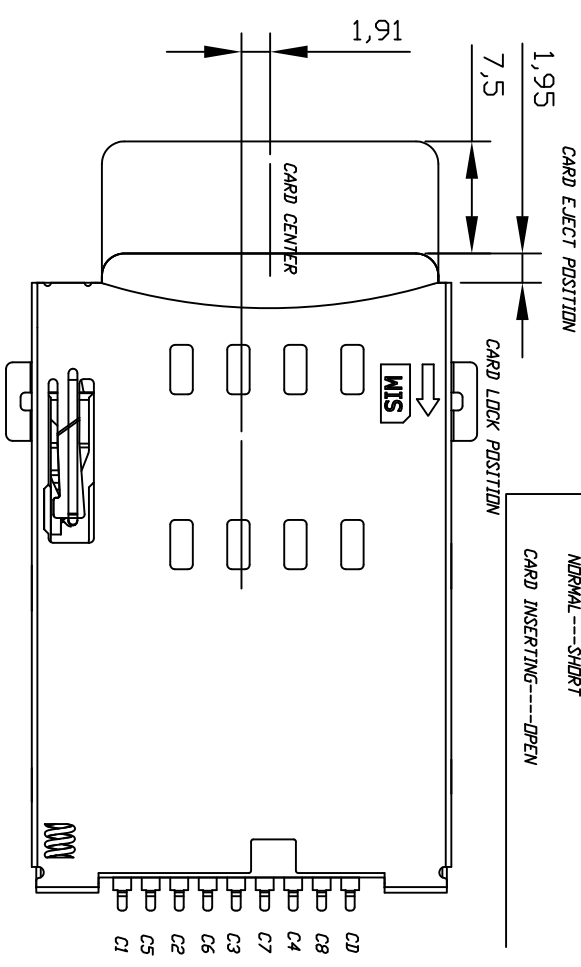
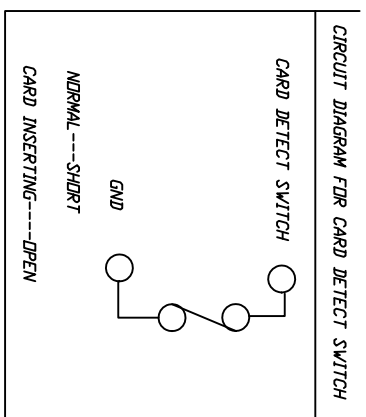
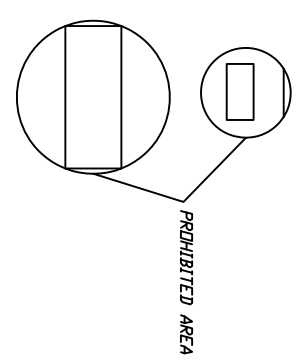
JIXING TECHNOLOGY CO.,LTD

THIRD ANGLE PROJECTION	SIZE:	SCALE:	SHEET NO:
	A4	---	1 OF 1

REV	DESCRIPTION	ECN NO	DATE



PCB PATTERN LAYOUT(+/-0.05MM)



NOTE:
 MATERIAL:
 1>HOUSING/HART-CAM:HI-TEMP PLASTIC UL94V-0 BLACK.
 2>TERMINAL: COPPER ALLOY.
 3>SHELL/CAM PIN/SPRING: STAINLESS STEEL
 FINISH:
 TML:1.25-6.25 MICRON NICKEL MIN UNDER-PLATED GOLD FLASH PLATD
 ON CONTACT AREA AND SOLDER TAIL.
 SHELL:GOLD FLASH OVER NICKEL UNDER-PLATED ON SOLDER PAD
 MECHANICAL SPEC:
 1>REPEATED 5000 TIMES MATING AND UNMATING CYCLES AND STILL MEAT ELECTRICAL
 CHARACTERISTICS.
 ELECTRICAL SPEC:
 1>RETED CURRENT(PER CONTACT):0.5AMPS MAX AND TEMPERATURE RISE SHOULD BE 30° MAX
 2>INSULATION RESISTANCE:100MEGOHMS MIN
 3>DIELECTRIC WITHSTANDING VOLTAGE:500VAC
 4>CONTACT RESISTANCE:100MILLIOHMS MAX

GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	TITLE:
XX	±0.25	JIXING TECHNOLOGY CO.,LTD
X.XX	±0.15	
X.XXX	±0.05	
	DRAWN BY: Frank	DATE: 11-7-9
	CHECKED BY:	DATE:
	APPERIAL BY:	DATE:
	PART NO:	TITLE:
		SIM Card Push T=1.50
		SIM-008(新改版-A)